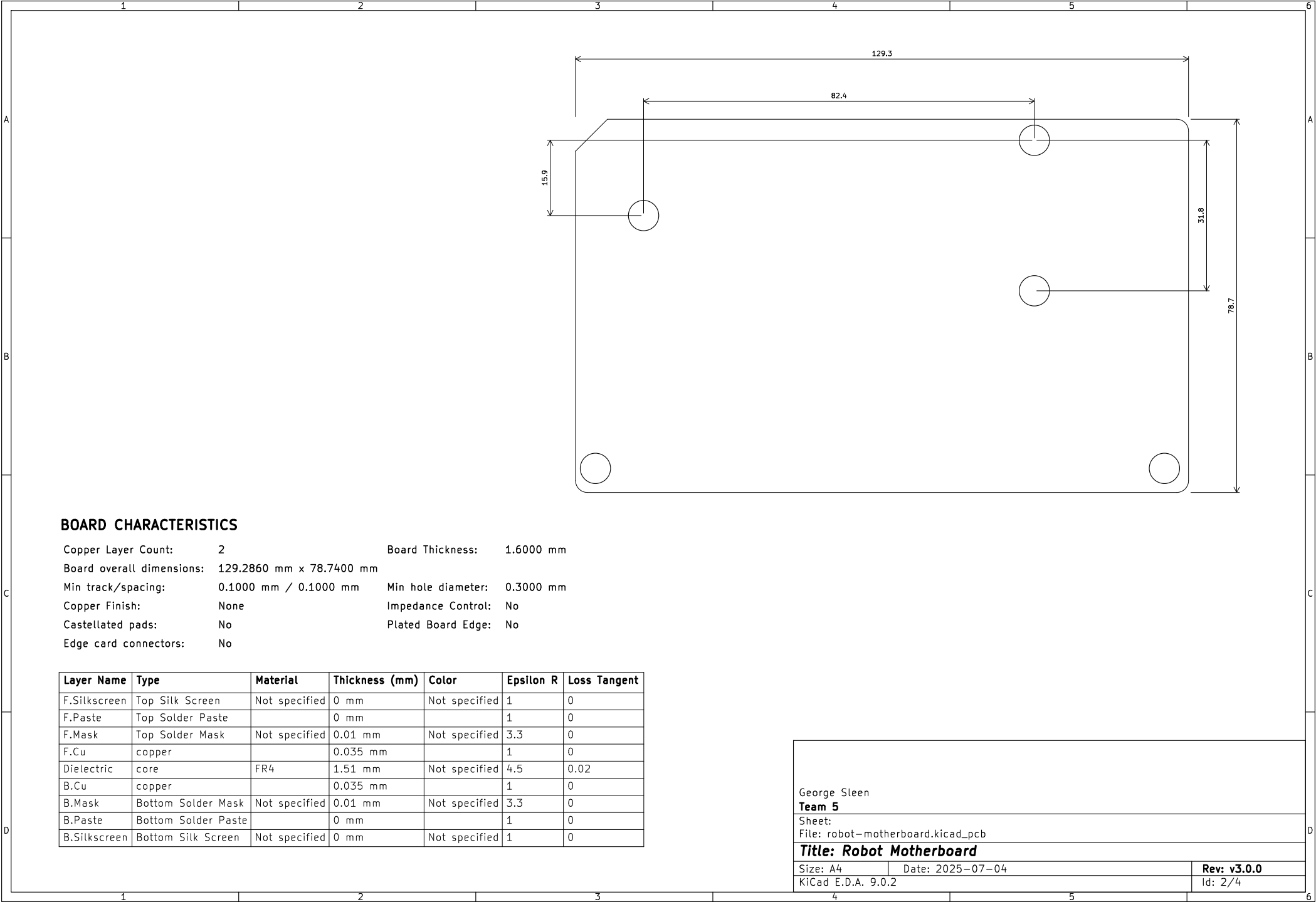


BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm
Board overall dimensions: 129.2860 mm x 78.7400 mm
Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.3000 mm
Copper Finish: None Impedance Control: No
Castellated pads: No Plated Board Edge: No
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

George Sleen	
Team 5	
Sheet:	
File: robot-motherboard.kicad_pcb	
Title: Robot Motherboard	
Size: A4	Date: 2025-07-04
KiCad E.D.A. 9.0.2	
Rev: v3.0.0	
Id: 1/4	



BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm

Board overall dimensions: 129.2860 mm x 78.7400 mm

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.3000 mm

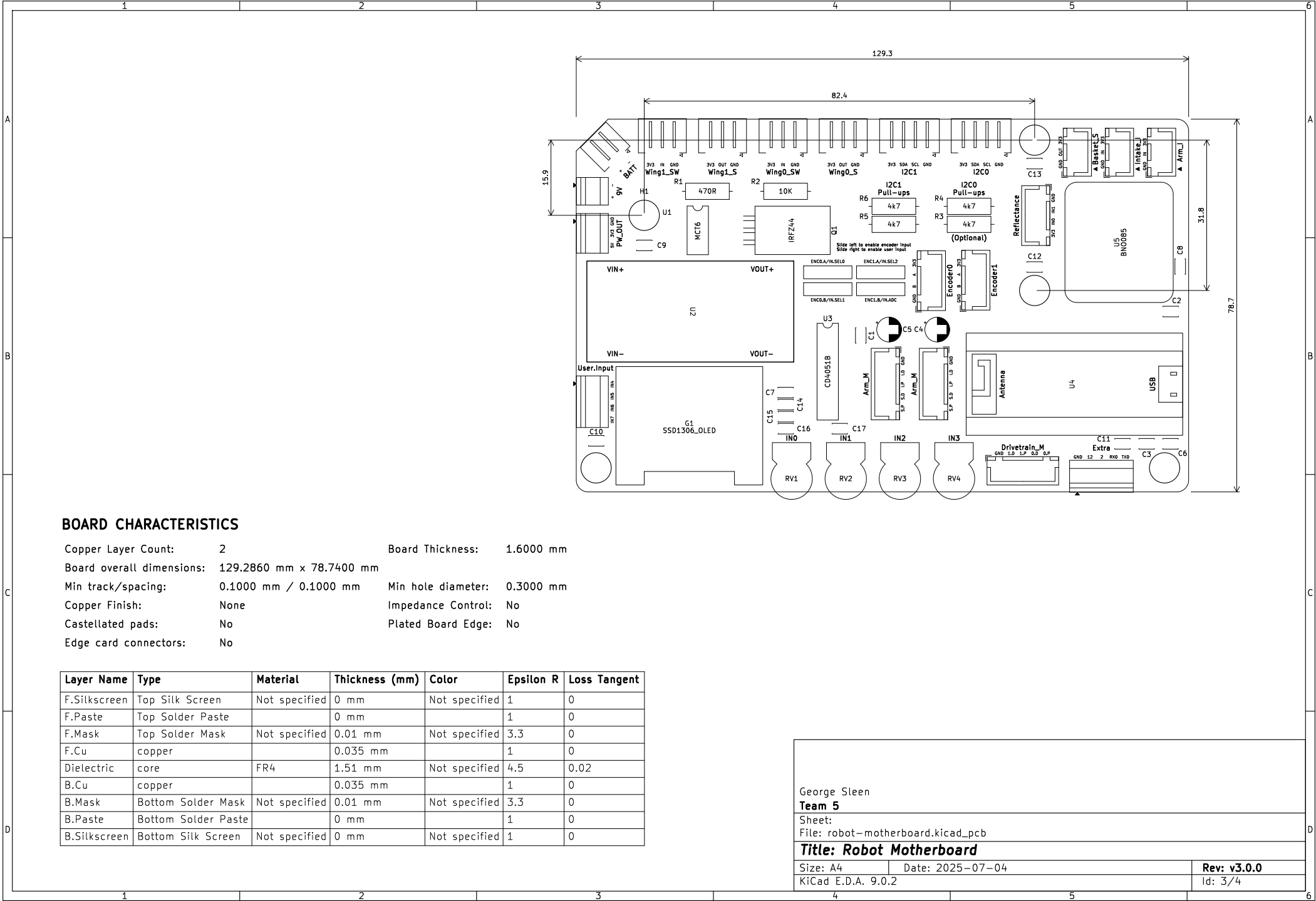
Copper Finish: None Impedance Control: No

Castellated pads: No Plated Board Edge: No

Edge card connectors: No

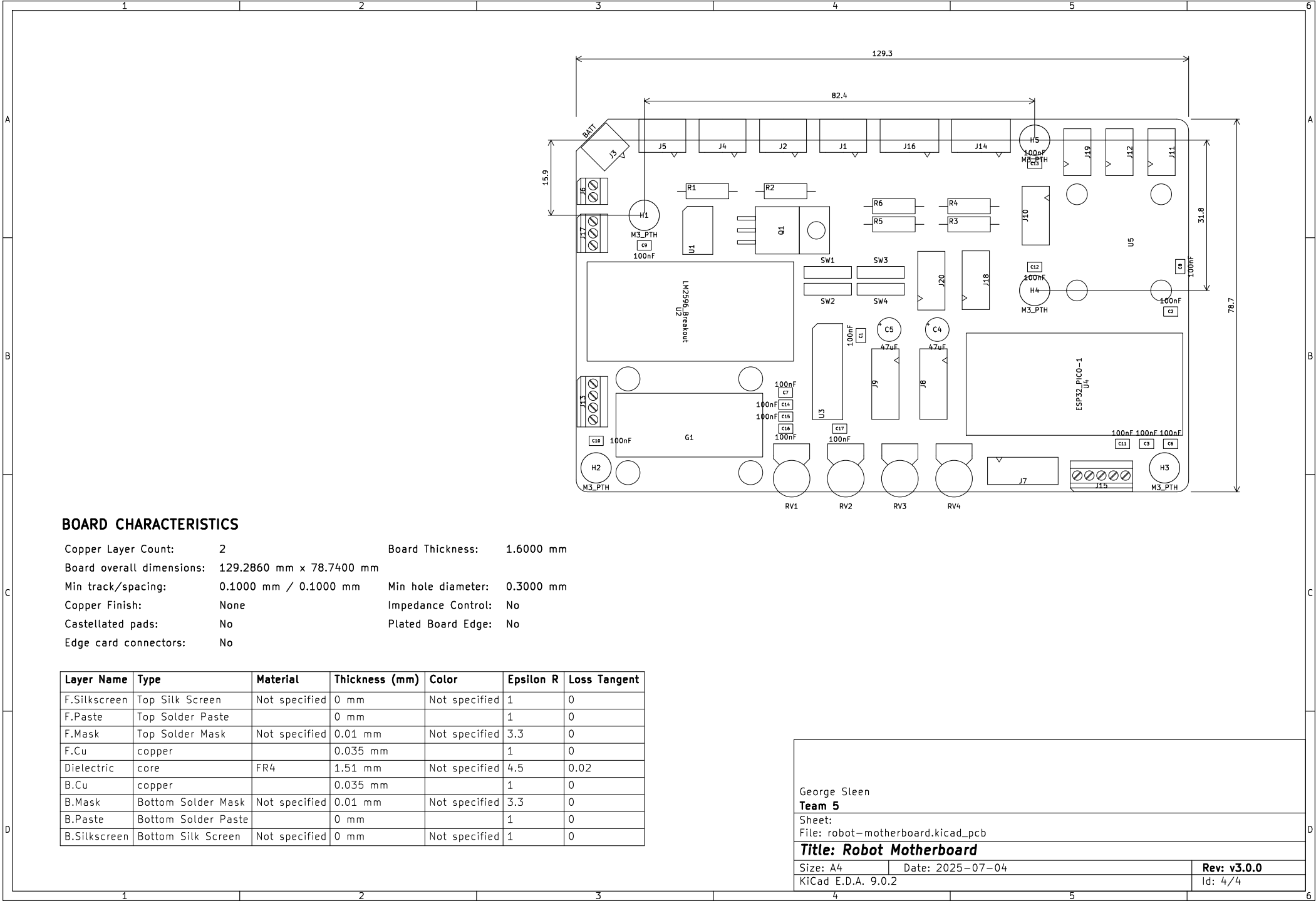
Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

George Sleen		
Team 5		
Sheet:		
File: robot-motherboard.kicad_pcb		
Title: Robot Motherboard		
Size: A4	Date: 2025-07-04	Rev: v3.0.0
KiCad E.D.A. 9.0.2		Id: 2/4



BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm
Board overall dimensions: 129.2860 mm x 78.7400 mm
Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.3000 mm
Copper Finish: None Impedance Control: No
Castellated pads: No Plated Board Edge: No
Edge card connectors: No



BOARD CHARACTERISTICS

Copper Layer Count: 2

Board Thickness: 1.6000 mm

Board overall dimensions: 129.2860 mm x 78.7400 mm

Min track/spacing: 0.1000 mm / 0.1000 mm

Min hole diameter: 0.3000 mm

Copper Finish: None

Impedance Control: No

Castellated pads: No

Plated Board Edge: No

Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

George Sleen

Team 5

Sheet:

File: robot-motherboard.kicad_pcb

Title: Robot Motherboard

Size: A4

Date: 2025-07-04

KiCad E.D.A. 9.0.2

Rev: v3.0.0

Id: 4/4